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(54) SEMICONDUCTOR DEVICE PACKAGING
STRUCTURE

the semiconductor device can be easily removed.

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(57) Abstract:

PROBLEM TO BE SOLVED: To provide a semiconductor device packaging structure which increases reliability in connection between connection terminal hidden in a package bottom surface and a printed board, and facilitates the packaging and removal of a semiconductor device.

SOLUTION: A semiconductor device 1 has guide pins 8 and conductive bumps 7. A printed board 11 has guide holes 13 for guiding the guide pins 8 and concave connection pads 14 to be in contact with the conductive bumps 7. When the semiconductor device 1 is packaged on the printed board 11, electrical connection is made by brazing the guide pins 8 to the guide holes 13, thus connecting the conductive bumps 7 to the connection pads 14. Accordingly, since it is unnecessary to braze a number of connection terminals, the packaging is simple. Further, short circuits due to the melting of the brazing material between adjacent connection pads is prevented. Further, as the semiconductor device 1 can be removed only by removing the braze of the guide pins 8.

